

IN THE CLAIMS:

Please note that all of the claims that remain pending and under consideration in the above-referenced application are reproduced below, in clean form, for the sake of clarity. Also, a marked-up version of each amended claim is enclosed herewith to clearly show each change that has been made thereto.

Please cancel claims 10 and 15 without prejudice or disclaimer.

Please enter the claims as follows:

1. (Amended) A semiconductor device, comprising:  
at least one bond pad positioned on a surface of a semiconductor device adjacent an edge thereof;  
and  
a layer comprising polymer on at least a portion of said surface, said layer having a notch formed therein which exposes at least a portion of said at least one bond pad.
2. (Amended) The semiconductor device of claim 1, wherein an edge portion of said layer adjacent said edge of said semiconductor die tapers from a surface of said layer toward said edge of said semiconductor die.
3. The semiconductor device of claim 2, wherein said edge portion of said layer comprises a bevel.
4. (Twice amended) The semiconductor device of claim 1, wherein said notch is tapered from a surface of said layer toward said surface of said semiconductor die.
5. The semiconductor device of claim 1, wherein said layer covers substantially all of said surface.
6. (Twice amended) The semiconductor device of claim 1, wherein said notch substantially surrounds said at least one bond pad.

7. (Amended) The semiconductor device of claim 1, including a plurality of bond pads.
8. (Amended) The semiconductor device of claim 7, wherein at least some of said bond pads are located adjacent said edge.
9. (Amended) The semiconductor device of claim 8, wherein said layer includes regions extending laterally between adjacent bond pads of said at least some bond pads.
11. (Amended) The semiconductor device of claim 1, wherein said polymer comprises a photoimageable material.
12. (Amended) A protective layer for a semiconductor die, comprising:  
a substantially planar member comprising polymer; and  
at least one notch formed adjacent an edge of said substantially planar member, said at least one notch being configured to expose at least a portion of a corresponding bond pad of the semiconductor die upon positioning the protective layer over an active surface of the semiconductor die.
13. (Previously amended) The protective layer of claim 12, further comprising a bevel along said edge.
14. The protective layer of claim 12, wherein at least one edge of said at least one notch is beveled.
16. (Amended) The protective layer of claim 12, wherein said polymer comprises a photoimageable material.

17. The protective layer of claim 12, including a plurality of notches located along said edge.

18. (Amended) The protective layer of claim 12, wherein said substantially planar member is configured to substantially cover said active surface of the semiconductor die upon assembly therewith.

19. (Twice amended) The protective layer of claim 12, wherein said substantially planar member is configured to cover only a portion of a surface of the semiconductor die adjacent an edge thereof proximate to which at least one bond pad is located upon assembly of the protective layer with the semiconductor die.

20. The protective layer of claim 12, wherein said at least one notch is formed in said edge.

21. (Twice amended) The protective layer of claim 12, wherein said at least one notch is configured to substantially surround the corresponding bond pad upon assembly of the protective layer with the semiconductor device.